

L Number	Hits	Search Text	DB	Time stamp
-	1	"6727167"	USPAT; US-PGPUB	2004/08/26 14:33
-	0	"20040171245"	USPAT;	2004/09/30 16:27
-	1	"20040171245"	USPAT; US-PGPUB	2004/09/30 16:27
-	2	"6727167"	USPAT; US-PGPUB	2004/09/30 16:39
-	139	438/602.ccls.	USPAT; US-PGPUB	2004/09/30 18:29
-	18	"6121127" "20010055871"	USPAT; US-PGPUB	2004/09/30 18:39
-	54	438/603.ccls. not (438/602.ccls.)	USPAT; US-PGPUB	2004/09/30 18:43
-	139	438/604.ccls. not (438/603.ccls. 438/602.ccls.)	USPAT; US-PGPUB	2004/09/30 18:54
-	115	438/605.ccls. not (438/604.ccls. 438/603.ccls. 438/602.ccls.)	USPAT; US-PGPUB	2004/09/30 19:01
-	107	438/606.ccls. not (438/605.ccls. 438/604.ccls. 438/603.ccls. 438/602.ccls.)	USPAT; US-PGPUB	2004/09/30 19:08
-	213	438/39.ccls. not (438/606.ccls. 438/605.ccls. 438/604.ccls. 438/603.ccls. 438/602.ccls.)	USPAT; US-PGPUB	2004/09/30 19:19
-	513	438/98.ccls. not (438/39.ccls. 438/606.ccls. 438/605.ccls. 438/604.ccls. 438/603.ccls. 438/602.ccls.)	USPAT; US-PGPUB	2004/09/30 19:29
-	859	(438/46.ccls. 438/47.ccls.) not (438/98.ccls. 438/39.ccls. 438/606.ccls. 438/605.ccls. 438/604.ccls. 438/603.ccls. 438/602.ccls.)	USPAT; US-PGPUB	2004/09/30 19:29
-	16	((438/46.ccls. 438/47.ccls.) not (438/98.ccls. 438/39.ccls. 438/606.ccls. 438/605.ccls. 438/604.ccls. 438/603.ccls. 438/602.ccls.)) and (electrode\$1 same (pattern\$5 near mask\$5))	USPAT; US-PGPUB	2004/09/30 19:32
-	4530	shibata.in.	USPAT; US-PGPUB	2004/09/30 19:32
-	420	shibata.in. and led	USPAT; US-PGPUB	2004/09/30 19:33
-	1	(shibata.in. and led) and metallization	USPAT; US-PGPUB	2004/09/30 19:33
-	221	(shibata.in. and led) and contact	USPAT; US-PGPUB	2004/09/30 19:42
-	17	((("4578343") or ("4615102") or ("4618510") or ("4742026") or ("4908325") or ("6021857") or ("5270228") or ("5288654") or ("5364816") or ("5468343") or ("5504353") or ("5563079") or ("5608239") or ("5610090") or ("5688387") or ("5824575") or ("5905277"))).PN.	USPAT	2004/09/30 20:00
-	787	(compound adj semiconductor) and (first adj electrode) and (second adj electrode)	USPAT; US-PGPUB	2004/09/30 20:29
-	121	((compound adj semiconductor) and (first adj electrode) and (second adj electrode)) and (first near region) and (second near region)	USPAT; US-PGPUB	2004/09/30 20:02
-	121	(compound adj semiconductor) and (first adj electrode) and (second adj electrode)	EPO; JPO; DERWENT; IBM_TDB	2004/09/30 20:53
-	1	2002-258815.NRAN.	DERWENT	2004/09/30 20:31
-	1	1994-334913.NRAN.	DERWENT	2004/09/30 20:36
-	1	1997-326199.NRAN.	DERWENT	2004/09/30 20:44
-	1	1997-556870.NRAN.	DERWENT	2004/09/30 20:45
-	12	(compound adj semiconductor) and ((metal near pattern\$5) with electrode)	EPO; JPO; DERWENT; IBM_TDB	2004/09/30 20:55
-	80	(compound adj semiconductor) and ((metal near pattern\$5) with electrode)	USPAT; US-PGPUB	2004/09/30 20:55
-	2	(nickel and gold and (anneal\$5 with transparent)) and (nickel with gold with (anneal\$5 with transparent))	USPAT; US-PGPUB	2004/09/30 22:52
-	9	(nickel Ni) with (gold Au) with (anneal\$5 with transparent)	USPAT; US-PGPUB	2004/09/30 22:52

-	98	nickel and gold and (anneal\$5 with transparent)	USPAT; US-PGPUB	2004/09/30 23:06
-	2265	(electron adj beam) with deposit\$5 with metal	USPAT; US-PGPUB	2004/09/30 23:06
-	1	((electron adj beam) with deposit\$5 with metal) and LED) and shibata.in.	USPAT; US-PGPUB	2004/09/30 23:07
-	202	((electron adj beam) with deposit\$5 with metal) and LED	USPAT; US-PGPUB	2004/09/30 23:07